BB02-EC

CUSTOMER PRODUCT SPECIFICATION SHEET

RoHS Compliant

BB02-EC :- 1.27mm x 2.54mm (0.05" x 0.1") DUAL ROW SOCKET, STRAIGHT, THROUGH HOLE - 6 TO 70 CONTACT

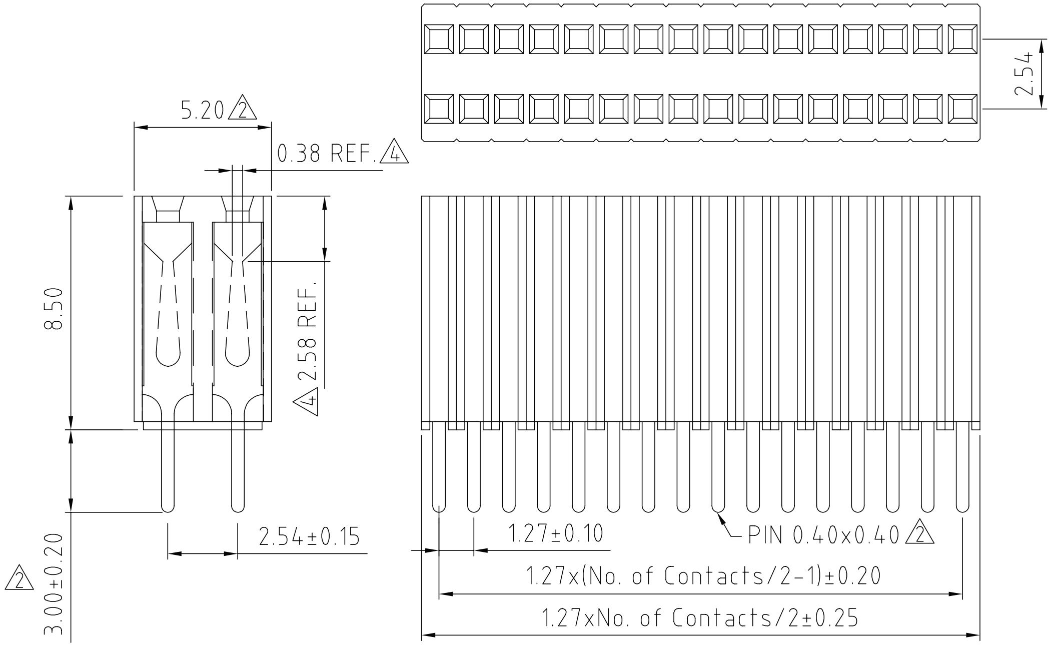
SPECIFICATIONS

CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	AC 300 V
CONTACT RESISTANCE	20m OHMS MAX.
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	POLYESTER UL 94V-0 STANDARD NYLON 6T
PLATING	GOLD, TIN OR SELECTIVE OVER 30~50U" NICKEL
SOLDERABILITY	IR REFLOW: 260°C FOR 10 SEC WAVE: 230°C FOR 5-10 SEC MANNUAL SOLDER: 350°C FOR 3-5 SEC

NOTES:

1. PACKED IN TUBE OR TRAY.
2. RECOMMANDED MATING PIN LENGTH: 4.5MM. △4

MATES WITH :- BB02-DA
BB02-DE
BB02-DF
BB02-DG



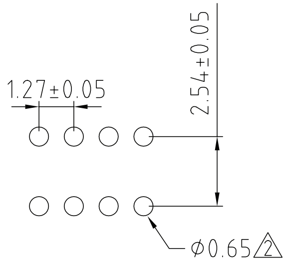
HOW TO ORDER

B	B	0	2	-	E	C	X	X	2	-	X	0	3	-	C	0	0	0	0	0

△2

NO. OF CONTACTS
△2 06 TO 70

CONTACT PLATING OPTIONS
K = GOLD FLASH (STANDARD)
A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
T = BRIGHT TIN
M = MATT TIN
D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL
E = 10U" GOLD ON CONTACT/BRIGHT TIN ON TAIL
F = 15U" GOLD ON CONTACT/BRIGHT TIN ON TAIL
G = 30U" GOLD ON CONTACT/BRIGHT TIN ON TAIL



RECOMMENDED PC BOARD HOLE LAYOUT
(TOLERANCE: ±0.05)

REV.	DATE & DRN
1.0	23/06/'02 - A.MCI RELEASE
1.1	12/02/'05 - NYW DRAWING MODIFICATION.
1.2 △2	21/072/'05 - NYW AMEND NO OF CONTACTS. AMEND INSULATOR DIM. AMEND PCB LAYOUT. AMEND PIN DIMENSION.
1.3	24/07/'06 - NYW DRAWING MODIFICATION.
1.4 △2	05/06/'07 - NYW ADD CONTACT DIM. ADD NOTES 2.
1.5	21/05/'08 - CHC PLATING MODIFICATION.
1.6	30/12/'08 - CHC DRAWING MODIFICATION.

Scale: 5:1	THIRD ANGLE	Unstated Tolerances: X. ± 0.30 .X ± 0.25 .XX ± 0.15 .XXX ± 0.10	Material SEE NOTE
Drawn: CHC			
App'd: XXXX	Title SOCKET		NOT TO SCALE
Date: 30 DEC '08	Revision: 1.6		UNIT: mm

Infratron®

Type: BB02-EC
BB02-EC
Drawing Number:
Sheet 1 of 1
Drawing © E and O E